

SOT1457-1

plastic low profile fine-pitch ball grid array package, 364 balls,
0.65 mm pitch, 15 mm x 15 mm x 1.3 mm body

30 September 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA364
Package type industry code	LFBGA364
Package style descriptive code	BGA (ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	02-03-2016
Manufacturer package code	98ASA01172D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	14.9	15	15.1	mm
package width	14.9	15	15.1	mm
seated height	1.2	1.3	1.45	mm
package height	0.95	1	1.1	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	364	-	



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2 Package outline

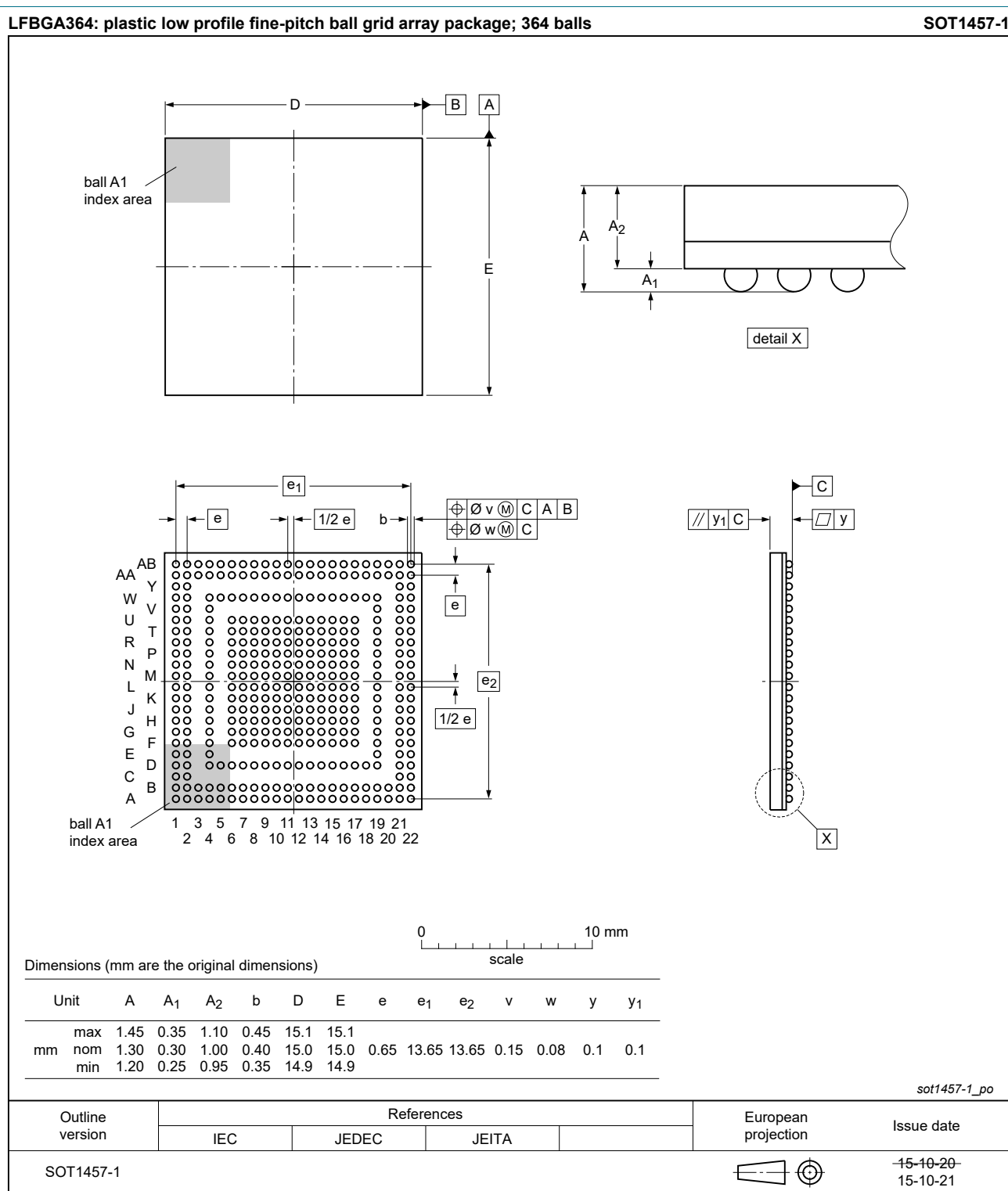
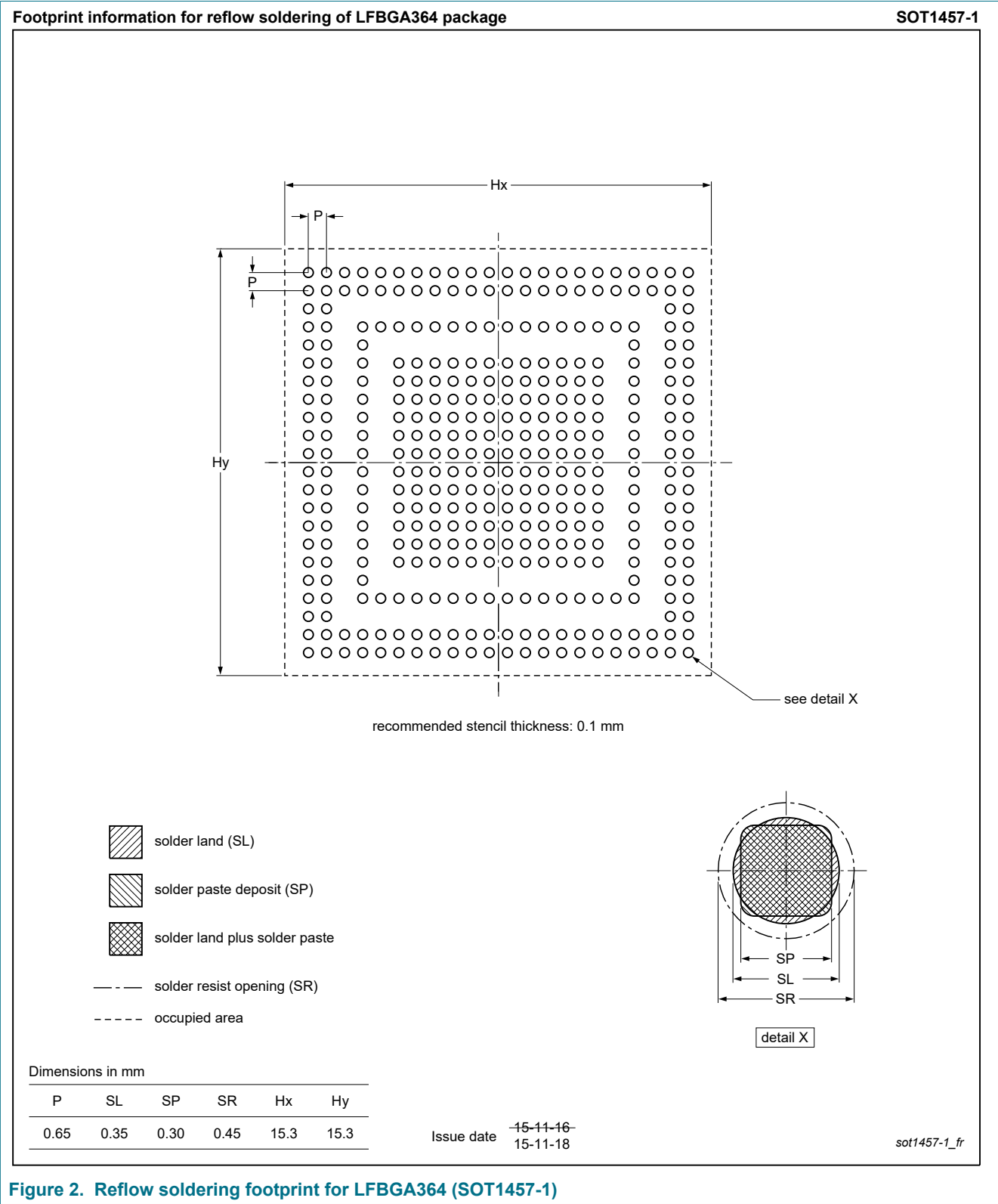


Figure 1. Package outline LFBGA364 (SOT1457-1)

3 Soldering



4 Legal information

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